Product / Process Change Notification



Corrections highlighted in blue print

2020-088-A

!! CONFIDENTIAL !!

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Additional assembly and final test location UTAC, Thailand for **PG-VQFN32-13**

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 25. September 2020.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG Postal Address Headquarters: Am Campeon 1-15, D-85579 Neubiberg, Phone +49 (0)89 234-0 Chairman of the Supervisory Board: Dr. Eckart Sünner Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider Registered Office: Neubiberg

Commercial Register: München HRB 126492

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▶ **Products affected:** Please refer to attached affected product list 1_cip20088_a

Detailed Change Information:

Subject: Additional assembly and final test location UTAC, Thailand for

PG-VQFN32-13

Reason: The additional assembly and test location is part of the Infineon strategy

to improve the delivery capability and flexibility with respect to customer's

demand and to safeguard delivery reliability.

Description: Old New Assembly and final test at Assembly and final test at AMKOR Technology - UTAC Thailand (UTAC) Philippines (ATP) - AMKOR Technology Philippines (ATP) Package name: Package name: PG-VQFN32-13 (ATP) PG-VQFN32-20 (UTAC) Package name: PG-VQFN32-13 (ATP) PG-VQFN32-20: PG-VQFN32-13: Die attach material (ATP): Die attach material (UTAC): CRM1085 Ablestik 8600 mold compound (ATP): Mold compound (UTAC): **EME G-700** EME G-700 LTD PG-VQFN32-13: Die attach material (ATP): CRM1085 Mold compound (ATP): **EME G-700**

▶ **Product Identification:** Traceability given by lot number and internal baunumber.

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► Impact of Change: No change of fit, form, function and reliability.

Changes are made for die attach material and mold compound material.

The packing material (e.g. Pizzabox, reel color, ...) are different at UTAC.

► Attachments: Affected product list 1_cip20088_a.xlsx

▶ Time Schedule:

■ Final qualification report: Available on request

■ First samples available: Available on request

■ Intended start of delivery: 15-November-2020

If you have any questions, please do not hesitate to contact your local Sales office.

PCN N° 2020-088-A

Additional assembly and final test location UTAC, Thailand for PG-VQFN32-13



Sales name	SP number	OPN	Package
SLB 9670VQ2.0 FW7.85	SP002510392	SLB9670VQ20FW785XUMA1	PG-VQFN-32-13
SLB 9670VQ2.0 FW7.85	SP002510396	SLB9670VQ20FW785XUMA2	PG-VQFN-32-13
SLB 9670VQ2.0 FW7.85	SP005344023	SLB9670VQ20FW785XTMA1	PG-VQFN-32-13